

Abstract of the Disclosure

Flip chip packages formed at a wafer level on semiconductor wafers for electronic systems provide convenient prepackaging. The package, in one embodiment, includes an adhesive layer applied to an active side of the wafer. The adhesive layer has openings to permit access to the conductive pads on each die. A conductive material substantially fills the openings. A pre-packaged die diced from the semiconductor wafer is mounted to a support wherein the conductive material effects electrical interconnection between the conductive pads on the die and receiving conductors on the support. The pre-packaged die can be coupled to a processor for an electronic system. To provide greater mounting densities, two or more dice may be coupled with the adhesive layer providing a covering for the two or more dice. The prepackaged chip with two or more dice may be coupled to a processor reducing the volume needed in an electronic system.

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